

SMD Comm COG, Ceramic, 8.2 pF, +/-0.25 pF, 50 VDC, COG, SMD, MLCC, Ultra-Stable, Low Loss, Class I, 0402



Dimensions

| Dimensions | |
|------------|-----------------|
| Chip Size | 0402 |
| L | 1mm +/-0.05mm |
| W | 0.5mm +/-0.05mm |
| T | 0.5mm +/-0.05mm |
| S | 0.3mm MIN |
| B | 0.3mm +/-0.1mm |

Packaging Specifications

| | |
|---------------------|------------------------|
| Packaging: | T&R, 330mm, Paper Tape |
| Packaging Quantity: | 50000 |

General Information

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|----------------|--|
| Series: | SMD Comm COG |
| Style: | SMD Chip |
| Description: | SMD, MLCC, Ultra-Stable, Low Loss, Class I |
| Features: | Ultra-Stable, Low Loss, Class I |
| RoHS: | Yes |
| Termination: | Tin |
| Marking: | No |
| AEC-Q200: | No |
| Miscellaneous: | Note: KEMET 50V rated parts may be operated at 63 Volts. |
| Shelf Life: | 78 Weeks |
| MSL: | 1 |

Specifications

| | |
|---|---------------------------|
| Capacitance: | 8.2 pF |
| Measurement Condition: | 1 MHz 1.0Vrms |
| Capacitance Tolerance: | +/-0.25 pF |
| Voltage DC: | 50 VDC |
| Dielectric Withstanding Voltage: | 125 VDC |
| Temperature Range: | -55/+125°C |
| Temperature Coefficient: | COG |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC): | 30 ppm/C, 1MegaHz 1.0Vrms |
| Dissipation Factor: | 0.1% 1 MHz 1.0Vrms |
| Aging Rate: | 0% Loss/Decade Hour |
| Insulation Resistance: | 100 GOhms |